

# EP2500TTSC-25.000M TR

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## REGULATORY COMPLIANCE (Data Sheet downloaded on Sep 9, 2018)


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## ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) HCMOS/TTL (CMOS) 5.0Vdc 4 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 25.000MHz  $\pm 100$ ppm -20°C to +70°C

## ELECTRICAL SPECIFICATIONS

|                                   |                                                                                                                                                                                                                                         |
|-----------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Nominal Frequency                 | 25.000MHz                                                                                                                                                                                                                               |
| Frequency Tolerance/Stability     | $\pm 100$ ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration) |
| Aging at 25°C                     | $\pm 5$ ppm/year Maximum                                                                                                                                                                                                                |
| Operating Temperature Range       | -20°C to +70°C                                                                                                                                                                                                                          |
| Supply Voltage                    | 5.0Vdc $\pm 10\%$                                                                                                                                                                                                                       |
| Input Current                     | 45mA Maximum (Unloaded)                                                                                                                                                                                                                 |
| Output Voltage Logic High (Voh)   | Vdd-0.4Vdc Minimum (IOH = -16mA)                                                                                                                                                                                                        |
| Output Voltage Logic Low (Vol)    | 0.4Vdc Maximum (IOL = +16mA)                                                                                                                                                                                                            |
| Rise/Fall Time                    | 4nSec Maximum (Measured at 20% to 80% of waveform)                                                                                                                                                                                      |
| Duty Cycle                        | 50 $\pm 5$ (%) (Measured at 1.4Vdc with TTL Load or 50% of waveform with HCMOS Load)                                                                                                                                                    |
| Load Drive Capability             | 50pF HCMOS Load Maximum                                                                                                                                                                                                                 |
| Output Logic Type                 | CMOS                                                                                                                                                                                                                                    |
| Pin 1 Connection                  | Tri-State (Disabled Output: High Impedance)                                                                                                                                                                                             |
| Pin 1 Input Voltage (Vih and Vil) | +2.0Vdc Minimum to enable output, +0.8Vdc Maximum to disable output, No Connect to enable output.                                                                                                                                       |
| Disable Current                   | 30mA Maximum (Pin 1 = Ground)                                                                                                                                                                                                           |
| Absolute Clock Jitter             | $\pm 250$ pSec Maximum, $\pm 100$ pSec Typical                                                                                                                                                                                          |
| One Sigma Clock Period Jitter     | $\pm 50$ pSec Maximum                                                                                                                                                                                                                   |
| Start Up Time                     | 10mSec Maximum                                                                                                                                                                                                                          |
| Storage Temperature Range         | -55°C to +125°C                                                                                                                                                                                                                         |

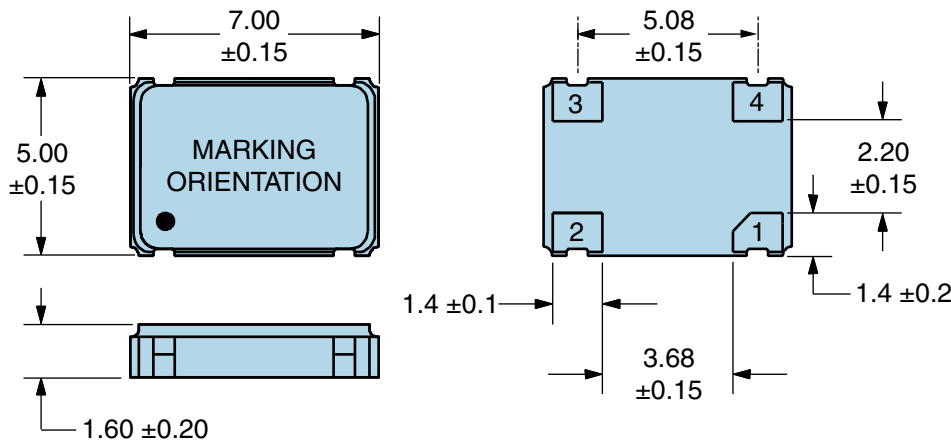
## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                              |                                               |
|------------------------------|-----------------------------------------------|
| ESD Susceptibility           | MIL-STD-883, Method 3015, Class 1, HBM: 1500V |
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A         |
| Flammability                 | UL94-V0                                       |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C         |
| Mechanical Shock             | MIL-STD-883, Method 2002, Condition B         |
| Moisture Resistance          | MIL-STD-883, Method 1004                      |
| Moisture Sensitivity         | J-STD-020, MSL 1                              |
| Resistance to Soldering Heat | MIL-STD-202, Method 210, Condition K          |
| Resistance to Solvents       | MIL-STD-202, Method 215                       |
| Solderability                | MIL-STD-883, Method 2003                      |
| Temperature Cycling          | MIL-STD-883, Method 1010, Condition B         |
| Vibration                    | MIL-STD-883, Method 2007, Condition A         |

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MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION                 |
|-----|----------------------------|
| 1   | Tri-State (High Impedance) |
| 2   | Ground/Case Ground         |
| 3   | Output                     |
| 4   | Supply Voltage             |

| LINE | MARKING                                               |
|------|-------------------------------------------------------|
| 1    | ECLIPTEK                                              |
| 2    | 25.000M                                               |
| 3    | XXXXXX<br>XXXXXX=Ecliptek<br>Manufacturing Identifier |

Suggested Solder Pad Layout

All Dimensions in Millimeters

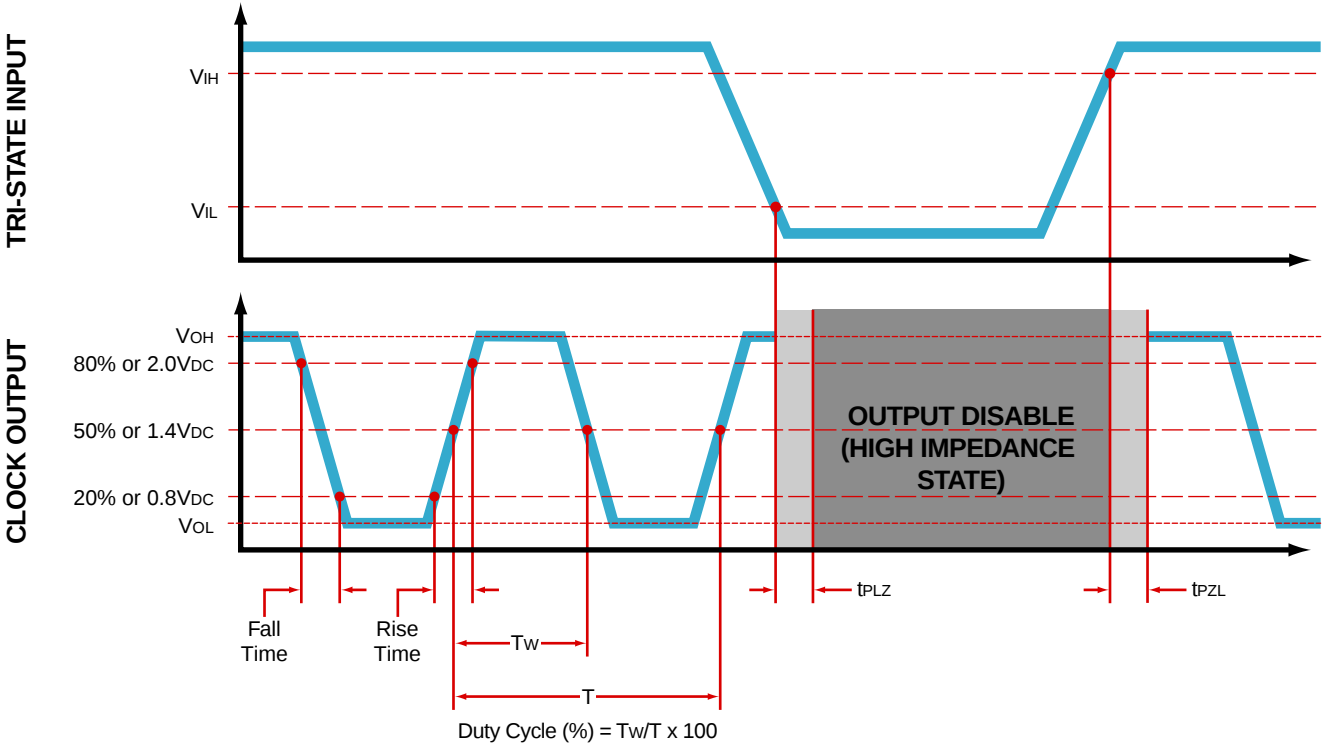


All Tolerances are ±0.1

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OUTPUT WAVEFORM & TIMING DIAGRAM



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## Test Circuit for CMOS Output



Note 1: An external 0.01  $\mu\text{F}$  ceramic bypass capacitor in parallel with a 0.1  $\mu\text{F}$  high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) passive probe is recommended.

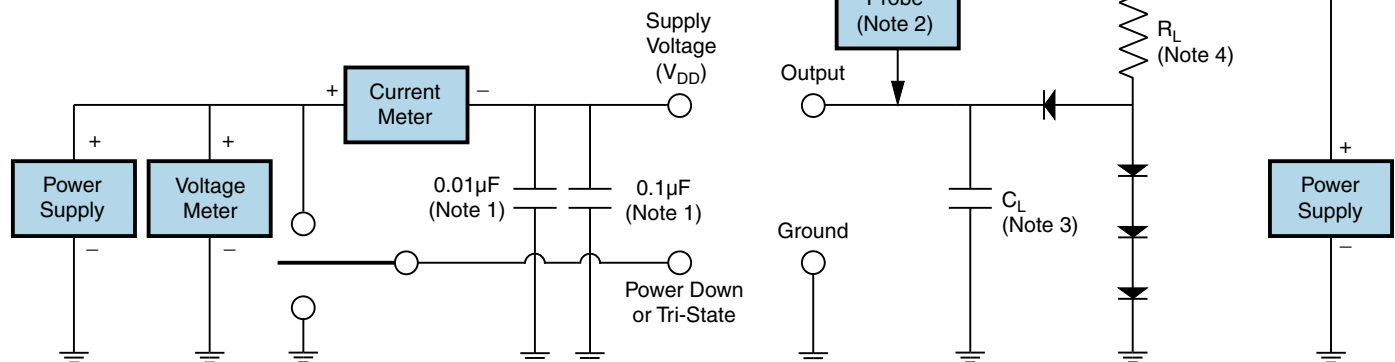
Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

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## Test Circuit for TTL Output

| Output Load<br>Drive Capability | R <sub>L</sub> Value<br>(Ohms) | C <sub>L</sub> Value<br>(pF) |
|---------------------------------|--------------------------------|------------------------------|
| 10TTL                           | 390                            | 15                           |
| 5TTL                            | 780                            | 15                           |

Table 1:  $R_L$  Resistance Value and  $C_L$  Capacitance Value Vs. Output Load Drive Capability



Note 1: An external 0.01 $\mu$ F ceramic bypass capacitor in parallel with a 0.1 $\mu$ F high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

Note 4: Resistance value  $R_L$  is shown in Table 1. See applicable specification sheet for 'Load Drive Capability'.

Note 5: All diodes are MMBD7000, MMBD914, or equivalent.



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Recommended Solder Reflow Methods



High Temperature Infrared/Convection

|                                     |                                                   |
|-------------------------------------|---------------------------------------------------|
| Ts MAX to TL (Ramp-up Rate)         | 3°C/Second Maximum                                |
| Preheat                             |                                                   |
| - Temperature Minimum (Ts MIN)      | 150°C                                             |
| - Temperature Typical (Ts TYP)      | 175°C                                             |
| - Temperature Maximum (Ts MAX)      | 200°C                                             |
| - Time (ts MIN)                     | 60 - 180 Seconds                                  |
| Ramp-up Rate (TL to TP)             | 3°C/Second Maximum                                |
| Time Maintained Above:              |                                                   |
| - Temperature (TL)                  | 217°C                                             |
| - Time (tL)                         | 60 - 150 Seconds                                  |
| Peak Temperature (TP)               | 260°C Maximum for 10 Seconds Maximum              |
| Target Peak Temperature (TP Target) | 250°C +0/-5°C                                     |
| Time within 5°C of actual peak (tp) | 20 - 40 Seconds                                   |
| Ramp-down Rate                      | 6°C/Second Maximum                                |
| Time 25°C to Peak Temperature (t)   | 8 Minutes Maximum                                 |
| Moisture Sensitivity Level          | Level 1                                           |
| Additional Notes                    | Temperatures shown are applied to body of device. |

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

|                                     |                                                        |
|-------------------------------------|--------------------------------------------------------|
| TS MAX to TL (Ramp-up Rate)         | 5°C/Second Maximum                                     |
| Preheat                             |                                                        |
| - Temperature Minimum (TS MIN)      | N/A                                                    |
| - Temperature Typical (TS TYP)      | 150°C                                                  |
| - Temperature Maximum (TS MAX)      | N/A                                                    |
| - Time (ts MIN)                     | 60 - 120 Seconds                                       |
| Ramp-up Rate (TL to TP)             | 5°C/Second Maximum                                     |
| Time Maintained Above:              |                                                        |
| - Temperature (TL)                  | 150°C                                                  |
| - Time (tL)                         | 200 Seconds Maximum                                    |
| Peak Temperature (TP)               | 240°C Maximum                                          |
| Target Peak Temperature (TP Target) | 240°C Maximum 2 Times / 230°C Maximum 1 Time           |
| Time within 5°C of actual peak (tP) | 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time |
| Ramp-down Rate                      | 5°C/Second Maximum                                     |
| Time 25°C to Peak Temperature (t)   | N/A                                                    |
| Moisture Sensitivity Level          | Level 1                                                |
| Additional Notes                    | Temperatures shown are applied to body of device.      |

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)